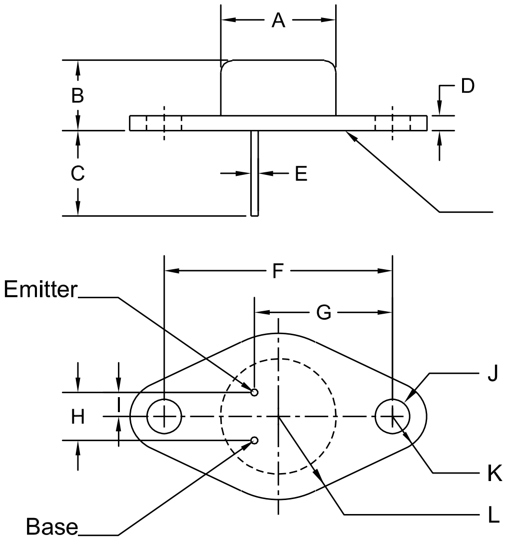
Package Details - TO-66

Mechanical Drawing



Seating Plane:
The seating plane must be within 0.001" concave to 0.004" convex within 0.600" diameter from the center of the device.

DIMENSIONS				
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A (DIA)	0.470	0.500	11.94	12.70
B	0.250	0.340	6.35	8.64
C	0.360	-	9.14	-
D	0.050	0.075	1.27	1.91
E (DIA)	0.028	0.034	0.71	0.86
F	0.958	0.962	24.33	24.43
G	0.570	0.590	14.48	14.99
H	0.190	0.210	4.83	5.33
I	0.093	0.107	2.36	2.72
J (DIA)	0.142	0.152	3.61	3.86
K (RAD)	0.145		3.68	
L (RAD)	0.350		8.89	

TO-66 (REV:R2)

Lead Code:
As indicated on mechanical drawing.

R2

Packing options:

Bulk - Packing Code: C
C = Anti-static coated plastic sleeves.
Bulk Packing Quantity: 30 per sleeve

Central™
Semiconductor Corp.
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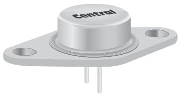
R0 (17-July 2008)

Material Composition Specification

TO-66 Case

Central Semiconductor Corp.



Device average mass . . . . **5.84 g**

Fluctuation margin . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.073%	4.28	doped Si	7440-21-3	0.073%	4.28	733
bond wire	aluminum	0.02%	1.15	Al	7429-90-5	0.02%	1.15	197
die attach	high temperature solder	0.37%	21.6	Pb	7439-92-1	0.342%	20.0	3,420
				Sn	7440-31-5	0.018%	1.08	185
				Ag	7440-22-4	0.009%	0.54	92
header	steel	83.38%	4,871	Fe	7439-89-6	82.55%	4,822	825,482
				Ni	7440-02-0	0.834%	48.7	8,339
can	alloy	15.5%	905	Fe	7439-89-6	15.34%	896	153,416
				Ni	7440-02-0	0.155%	9.05	1,549
die coating	Slygard 527	0.66%	38.5	silicone	--	0.659%	38.5	6,591
plating*	tin/lead process	.00009%	0.005	Sn	7440-31-5	.00007%	0.004	1
				Pb	7439-92-1	.00002%	0.001	0
	100% tin process	.00009%	0.005	Sn	7440-31-5	.00009%	0.005	1

*For Lead Free plating, add suffix "LEAD FREE" to part number.
For Tin/Lead plating, add suffix "TIN/LEAD" to part number.
No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R1 (3-June 2011)